IEEE P802.11  
Wireless LANs

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| TGbe Sept-Nov Teleconference Minutes | | | | |
| Date: 2022-12-14 | | | | |
| Author(s): | | | | |
| Name | Affiliation | Address | Phone | email |
| Jason Yuchen Guo | Huawei |  |  | guoyuchen@huawei.com |
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|  |  |  |  |  |

Abstract

This document contains the minutes for the IEEE 802.11 TGbe teleconferences from November 2022 to January 2023.

Revision history:

* Rev0: initial version of the document
* Rev1: add the validated result for motion 486
* Rev2: add the minutes for the January 04 Joint meeting and the links for the MAC Ad-Hoc meetings.

Abbreviations:

* C: Comment.
* A: Answer.

# 1st Conf. Call: November 30 (10:00–12:00 ET)–MAC

Please refer to the following link for the minutes

* https://mentor.ieee.org/802.11/dcn/22/11-22-2080-02-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-nov-2022-to-jan-2023.docx

# 2nd Conf. Call: December 01 (10:00–12:00 ET)–MAC

Please refer to the following link for the minutes

* https://mentor.ieee.org/802.11/dcn/22/11-22-2080-02-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-nov-2022-to-jan-2023.docx

# 3rd Conf. Call: December 05 (19:00–21:00 ET)–MAC

Please refer to the following link for the minutes

* https://mentor.ieee.org/802.11/dcn/22/11-22-2080-02-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-nov-2022-to-jan-2023.docx

# 4th Conf. Call: December 07 (10:00–12:00 ET)–MAC

Please refer to the following link for the minutes

* https://mentor.ieee.org/802.11/dcn/22/11-22-2080-05-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-nov-2022-to-jan-2023.docx

# 5th Conf. Call: December 14 (10:00–12:00 ET)–JOINT

* The Chair, Alfred Asterjadhi (Qualcomm), calls the meeting to order
* The Chair presents the IEEE 802 and 802.11 IPR policy and procedure
  + **Patent Policy: Ways to inform IEEE:**
    - Cause an LOA to be submitted to the IEEE-SA ([patcom@ieee.org](mailto:patcom@ieee.org)); or
    - Provide the chair of this group with the identity of the holder(s) of any and all such claims as soon as possible; or
    - Speak up now and respond to this Call for Potentially Essential Patents

If anyone in this meeting is personally aware of the holder of any patent claims that are potentially essential to implementation of the proposed standard(s) under consideration by this group and that are not already the subject of an Accepted Letter of Assurance, please respond at this time by providing relevant information to the WG Chair. **Nobody speaks/writes up**.

* + **Copyright Policy: Participants are advised that**
    - IEEE SA’s copyright policy is described in [Clause 7](https://standards.ieee.org/about/policies/bylaws/sect6-7.html#7) of the IEEE SA Standards Board Bylaws and [Clause 6.1](https://standards.ieee.org/about/policies/opman/sect6.html) of the IEEE SA Standards Board Operations Manual;
    - Any material submitted during standards development, whether verbal, recorded, or in written form, is a Contribution and shall comply with the IEEE SA Copyright Policy

**Copyright Policy was presented.**

* + **Patent, Participation, Copyright and policy related subclause:** Please refer to Patent And Procedures
* Attendance reminder.
  + Participation slide: <https://mentor.ieee.org/802-ec/dcn/16/ec-16-0180-05-00EC-ieee-802-participation-slide.pptx>
  + Please record your attendance during the conference call by using the IMAT system:
    - 1) login to [imat](https://imat.ieee.org/attendance), 2) select “802.11 Telecons (<Month>)” entry, 3) select “C/LM/WG802.11 Attendance” entry, 4) click “<Joint TGbe > conference call that you are attending.
  + If you are unable to record the attendance via [IMAT](https://imat.ieee.org/attendance) then please send an e-mail to Jason Y. Guo ([guoyuchen@huawei.com](mailto:guoyuchen@huawei.com)) and Alfred Asterjadhi ([asterjadhi@gmail.com](mailto:asterjadhi@gmail.com))
  + Please ensure that the following information is listed correctly when joining the call:
    - "[voter status] First Name Last Name (Affiliation)"
  + Attendee List

|  |  |  |  |
| --- | --- | --- | --- |
| Breakout | Timestamp | Name | Affiliation |
| TGbe (Joint)\* | 12/14 | Adhikari, Shubhodeep | Broadcom Corporation |
| TGbe (Joint)\* | 12/14 | Ajami, Abdel Karim | Qualcomm Technologies, Inc |
| TGbe (Joint)\* | 12/14 | Awater, Geert | Qualcomm Incorporated |
| TGbe (Joint)\* | 12/14 | Baek, SunHee | LG ELECTRONICS |
| TGbe (Joint)\* | 12/14 | Borges, Daniel | Apple, Inc. |
| TGbe (Joint)\* | 12/14 | Bredewoud, Albert | Broadcom Corporation |
| TGbe (Joint)\* | 12/14 | Chen, You-Wei | MediaTek Inc. |
| TGbe (Joint)\* | 12/14 | CHENG, yajun | Xiaomi Communications Co., Ltd. |
| TGbe (Joint)\* | 12/14 | Chu, Liwen | NXP Semiconductors |
| TGbe (Joint)\* | 12/14 | CHUN, JINYOUNG | LG ELECTRONICS |
| TGbe (Joint)\* | 12/14 | Chung, Chulho | SAMSUNG |
| TGbe (Joint)\* | 12/14 | Coffey, John | Realtek Semiconductor Corp. |
| TGbe (Joint)\* | 12/14 | Dong, Xiandong | Xiaomi Communications Co., Ltd. |
| TGbe (Joint)\* | 12/14 | Fan, Shuang | ZTE Corporation |
| TGbe (Joint)\* | 12/14 | Fang, Yonggang | Mediatek |
| TGbe (Joint)\* | 12/14 | Fischer, Matthew | Broadcom Corporation |
| TGbe (Joint)\* | 12/14 | Fujimori, Yuki | Canon Research Centre France |
| TGbe (Joint)\* | 12/14 | Garg, Lalit | Broadcom Corporation |
| TGbe (Joint)\* | 12/14 | Gu, Xiangxin | Unisoc |
| TGbe (Joint)\* | 12/14 | GUIGNARD, Romain | Canon Research Centre France |
| TGbe (Joint)\* | 12/14 | Gupta, Binita | Meta Platforms, Inc. |
| TGbe (Joint)\* | 12/14 | Handte, Thomas | Sony Corporation |
| TGbe (Joint)\* | 12/14 | Hotchkiss, Ron | IEEE STAFF |
| TGbe (Joint)\* | 12/14 | Huang, Lei | Huawei International Pte Ltd |
| TGbe (Joint)\* | 12/14 | Huang, Po-Kai | Intel |
| TGbe (Joint)\* | 12/14 | Huq, Kazi Mohammed Saidul | Ofinno |
| TGbe (Joint)\* | 12/14 | Kakani, Naveen | Qualcomm Incorporated |
| TGbe (Joint)\* | 12/14 | Kamel, Mahmoud | InterDigital, Inc. |
| TGbe (Joint)\* | 12/14 | Kasher, Assaf | Qualcomm Incorporated |
| TGbe (Joint)\* | 12/14 | Kim, Myeong-Jin | SAMSUNG |
| TGbe (Joint)\* | 12/14 | Kim, Sang Gook | LG ELECTRONICS |
| TGbe (Joint)\* | 12/14 | Kim, Sanghyun | WILUS Inc |
| TGbe (Joint)\* | 12/14 | Kim, Youhan | Qualcomm Technologies, Inc. |
| TGbe (Joint)\* | 12/14 | Kishida, Akira | Nippon Telegraph and Telephone Corporation (NTT) |
| TGbe (Joint)\* | 12/14 | Klein, Arik | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 12/14 | Kneckt, Jarkko | Apple, Inc. |
| TGbe (Joint)\* | 12/14 | Ko, Geonjung | WILUS Inc. |
| TGbe (Joint)\* | 12/14 | Koundourakis, Michail | Samsung Cambridge Solution Centre |
| TGbe (Joint)\* | 12/14 | Li, Yapu | Guangdong OPPO Mobile Telecommunications Corp.,Ltd |
| TGbe (Joint)\* | 12/14 | Liu, Der-Zheng | Realtek Semiconductor Corp. |
| TGbe (Joint)\* | 12/14 | Liu, Yong | Apple, Inc. |
| TGbe (Joint)\* | 12/14 | Lorgeoux, Mikael | Canon Research Centre France |
| TGbe (Joint)\* | 12/14 | Lou, Hanqing | InterDigital, Inc. |
| TGbe (Joint)\* | 12/14 | Lu, kaiying | MediaTek Inc. |
| TGbe (Joint)\* | 12/14 | Lu, Liuming | Guangdong OPPO Mobile Telecommunications Corp.,Ltd |
| TGbe (Joint)\* | 12/14 | Malinen, Jouni | Qualcomm Technologies, Inc |
| TGbe (Joint)\* | 12/14 | MAO, ZHI | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 12/14 | McCann, Stephen | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 12/14 | Naik, Gaurang | Qualcomm Technologies, Inc |
| TGbe (Joint)\* | 12/14 | Nam, Junyoung | Qualcomm Incorporated |
| TGbe (Joint)\* | 12/14 | Nayak, Peshal | Samsung Research America |
| TGbe (Joint)\* | 12/14 | Nezou, Patrice | Canon Research Centre France |
| TGbe (Joint)\* | 12/14 | Pandey, Sheetal | ON Semiconductor |
| TGbe (Joint)\* | 12/14 | Pare, Thomas | MediaTek Inc. |
| TGbe (Joint)\* | 12/14 | Park, Minyoung | Intel |
| TGbe (Joint)\* | 12/14 | Park, Sungjin | Senscomm |
| TGbe (Joint)\* | 12/14 | Patil, Abhishek | Qualcomm Incorporated |
| TGbe (Joint)\* | 12/14 | Patwardhan, Gaurav | Hewlett Packard Enterprise |
| TGbe (Joint)\* | 12/14 | Quan, Yingqiao | Unisoc |
| TGbe (Joint)\* | 12/14 | Rai, Kapil | Qualcomm Incorporated |
| TGbe (Joint)\* | 12/14 | Ratnam, Vishnu | Samsung Research America |
| TGbe (Joint)\* | 12/14 | Redlich, Oded | Huawei Technologies Co., Ltd; Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 12/14 | Ryu, Kiseon | NXP Semiconductors |
| TGbe (Joint)\* | 12/14 | Sato, Takuhiro | SHARP CORPORATION |
| TGbe (Joint)\* | 12/14 | Schelstraete, Sigurd | MaxLinear |
| TGbe (Joint)\* | 12/14 | Shafin, Rubayet | Samsung Research America |
| TGbe (Joint)\* | 12/14 | Shu, Tongxin | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 12/14 | SUH, JUNG HOON | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 12/14 | Sun, Bo | Sanechips |
| TGbe (Joint)\* | 12/14 | Sun, Yanjun | Qualcomm Incorporated |
| TGbe (Joint)\* | 12/14 | Tadahal, Shivkumar | Broadcom Corporation |
| TGbe (Joint)\* | 12/14 | Taori, Rakesh | Infineon Technologies |
| TGbe (Joint)\* | 12/14 | Thakur, Sidharth | Apple, Inc. |
| TGbe (Joint)\* | 12/14 | Tsodik, Genadiy | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 12/14 | Tsujimaru, Yuki | Canon Inc. |
| TGbe (Joint)\* | 12/14 | Van Zelst, Allert | Qualcomm Technologies Netherlands B.V. |
| TGbe (Joint)\* | 12/14 | Verma, Lochan | Apple, Inc. |
| TGbe (Joint)\* | 12/14 | Verma, Sindhu | Broadcom Corporation |
| TGbe (Joint)\* | 12/14 | Wang, Chao Chun | MediaTek Inc. |
| TGbe (Joint)\* | 12/14 | Wang, Qi | Apple, Inc. |
| TGbe (Joint)\* | 12/14 | Wei, Dong | NXP Semiconductors |
| TGbe (Joint)\* | 12/14 | Wentink, Menzo | Qualcomm Incorporated |
| TGbe (Joint)\* | 12/14 | Wu, Kanke | Qualcomm Incorporated |
| TGbe (Joint)\* | 12/14 | Wullert, John | Peraton Labs |
| TGbe (Joint)\* | 12/14 | Xia, Qing | Sony Corporation |
| TGbe (Joint)\* | 12/14 | Yang, Steve TS | MediaTek Inc. |
| TGbe (Joint)\* | 12/14 | Yano, Kazuto | Advanced Telecommunications Research Institute International (ATR) |
| TGbe (Joint)\* | 12/14 | Yee, James | MediaTek Inc. |
| TGbe (Joint)\* | 12/14 | Yi, Yongjiang | Spreadtrum Communication USA, Inc |
| TGbe (Joint)\* | 12/14 | Yong, Su Khiong | Apple, Inc. |
| TGbe (Joint)\* | 12/14 | Yu, Jian | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 12/14 | Zhang, Jiayi | Ofinno |
| TGbe (Joint)\* | 12/14 | Zhou, Pei | Guangdong OPPO Mobile Telecommunications Corp.,Ltd |

* Announcements:
* Queue Status for LB266 CR (based on [11-22/0971r36](https://mentor.ieee.org/802.11/dcn/22/11-22-0971-36-00be-ieee-802-11be-lb266-comments.xlsx)): 861 pending CIDs
  + **Assigned with DCN:** 49 CIDs that are assigned and are present in a submission and expected to be in the queues pending presentation.
    - **AI for members:** Please verify the presence of the submissions in the queues.
    - **How to find these:** in the spreadsheet filter with Status column to “Assigned” and Submission column not “Blank”.
  + **Assigned without DCN:** 329 CIDs that are assigned but there is no DCN for them, and hence they are expected not to be in the queues pending presentation.
    - **AI for members:** If you are a POC and the CIDs assigned to you fall into this category please make sure that you provide the DCN that will contain these CIDs by December 15, 2022 and that the DCN is added to the queues for presentation. CIDs that do not have a DCN after the deadline may need to be reassigned to other volunteers so that we resolve them by the deadline.
    - **How to find these:** Either check e-mails sent by Edward or filter the spreadsheet with Status column to “Assigned” and Submission column set to “Blank”.
  + **Resolution Drafted:** 441 CIDs that have been presented but no consensus yet.
    - These CIDs are in a presentation that has been presented at some point but have not had consensus yet. Note that if any of these CIDs is presented more than 2 weeks ago and are not pending SP then they are expected to end up in quarantine.
    - Some of these CIDs are requested to be further discussed by members in post-quarantine. These requests are tracked in the post-Quarantine queues (currently there are 35 docs in this queue with pending SP). These SPs expected to run only after the CIDs that are not resolve and yet to be presented are resolved.
      * **AI for members:** Check that all the CIDs that were requested for deferral and pending SP have the most up to date DCN (several docs are currently missing (tagged as xxxx)).
      * **How to find these:** These are found towards the end of the MAC queue (post-quarantine) in the agenda.
* Agenda
  + Technical Submissions**: CRs**
    - [1423r3](https://mentor.ieee.org/802.11/dcn/22/11-22-1423-03-00be-eht-smps.docx) EHT SMPS Xiaogang Chen [SP 10’]
    - [1482r2](https://mentor.ieee.org/802.11/dcn/22/11-22-1482-02-00be-lb266-cr-for-preamble-puncturing.docx) CR for preamble puncturing Yanjun Sun [2C-SP 10’]
    - [1695r0](https://mentor.ieee.org/802.11/dcn/22/11-22-1695-00-00be-cr-on-cid-11827-and-12115.docx) CR on CID 11827 and 12115 Jinyoung Chun [1C-SP 10’]
    - 1565r3 CR for UORA Geonjung Ko [5C 10’]
    - …
  + Motions (second hour): [1038r28](https://mentor.ieee.org/802.11/dcn/22/11-22-1038-28-00be-tgbe-motions-list-part-3.pptx)
  + Technical Submissions:
    - …
  + Discussions
    - Xiangxin asked to add 1321r3 and 1815r1 to the queue
    - Yanjun asked to defer 1482r2, and add 2123r0
    - Subir asked to add 1864 to the queue
  + Agenda approved with unanimous consent
* Discussions of the Technical Submissions**: CRs**
  + [1423r3](https://mentor.ieee.org/802.11/dcn/22/11-22-1423-03-00be-eht-smps.docx) EHT SMPS Xiaogang Chen

C: Timeline is a concern, it is difficult to do it in TGbe, we can discuss it in UHR.

A: for some features in MLO, they also need changes. I think this feature requires less change than the MLO features.

C: it is not that straight forward, it has a lot of other implications.

**SP:** Do you agree to incorporate the text changes in 11-22/1423r2 into the latest TGbe draft?

Discussion: None.

Result: 23Y/31N/39A

* + [1695r0](https://mentor.ieee.org/802.11/dcn/22/11-22-1695-00-00be-cr-on-cid-11827-and-12115.docx) CR on CID 11827 and 12115 Jinyoung Chun

C: the note is saying RDG is not in the MU-RTS TXS Trigger frame, is it a wording issue?

Some wording changes are made on the fly which addresses the comment.

**SP:** Do you agree to resolve the following CIDs listed in 11-22/1695r1 and incorporate the text changes into the latest TGbe draft?

         11827

Discussion: None.

Result: No objection

* + 1565r3 CR for UORA Geonjung Ko

**SP:** Do you agree to resolve the following CIDs listed in 11-22/1565r3 and incorporate the text changes into the latest TGbe draft?

         13550, 13958, 10802, 10957, 12491, 12492, 14052, 14050

Discussion: None.

Result: No objection

* + 2123r0 LB266 CR for Trigger frame Misc Part1 Yanjun Sun

**SP:** Do you agree to resolve the following CIDs listed in 11-22/2123r0 and incorporate the text changes into the latest TGbe draft?

         10979, 10958, 13549, 13440, 10813

Discussion: None.

Result: No objection

* + Motions

**Motion 480 (JOINT)**

**Move to approve resolutions to the CIDs:**

* 10233, 13360 in [11-22/1647r1](https://mentor.ieee.org/802.11/dcn/22/11-22-1647-01-00be-crs-for-11be-d2-0-ml-security-cids.docx) [2 CIDs]

**and incorporate the text changes into the latest TGbe draft.**

**Move: Edward Au Second: Abhishek Patil**

**Discussion: None.**

**Result: Approved with unanimous consent.**

**Motion 481 (MAC)**

**Move to approve resolutions to the CIDs:**

* 12588, 13873 in [11-22/1881r4](https://mentor.ieee.org/802.11/dcn/22/11-22-1881-04-00be-lb266-cr-for-leftover-cids.docx) & 14036, 14037, 14073 in [11-22/1846r4](https://mentor.ieee.org/802.11/dcn/22/11-22-1846-04-00be-cr-for-nstrmobileap-part3.docx) *[5 CIDs]*
* 11377, 11378, 12089, 13120, 13121 in [11-22/1887r0](https://mentor.ieee.org/802.11/dcn/22/11-22-1887-00-00be-lb266-cids-on-group-addressed-frame-duplicate-detection.docx) *[5 CIDs]*
* 10036 in [11-22/1768r6](https://mentor.ieee.org/802.11/dcn/22/11-22-1768-06-00be-lb266-cr-for-subclause-35-3-16-8-1.docx) & 13128 in [11-22/1766r3](https://mentor.ieee.org/802.11/dcn/22/11-22-1766-03-00be-lb266-cr-for-various-cids.docx) & 11752, 13517, 12111 in [11-22/1747r5](https://mentor.ieee.org/802.11/dcn/22/11-22-1747-05-00be-lb266-cr-for-subclause-35-3-15.docx) [5 CIDs]
* 12170, 12171 in [11-22/1833r1](https://mentor.ieee.org/802.11/dcn/22/11-22-1833-01-00be-lb266-cr-for-35-3-7-1-3.docx) & 10364 in [11-22/1417r2](https://mentor.ieee.org/802.11/dcn/22/11-22-1417-02-00be-lb266-cr-for-35-3-16-2.docx) & 11838 in [11-22/1744r2](https://mentor.ieee.org/802.11/dcn/22/11-22-1744-02-00be-lb266-cr-for-miscellaneous-cids.docx) *[4 CIDs]*
* 10032, 12331, 10658, 11646, 13853, 13074, 14034, 14004 in [11-22/1793r4](https://mentor.ieee.org/802.11/dcn/22/11-22-1793-04-00be-nstr-mobile-ap-miscellaneous-cids.docx) *[8 CIDs]*
* 11111, 11117, 12461 in [11-22/1774r3](https://mentor.ieee.org/802.11/dcn/22/11-22-1774-03-00be-lb266-cr-for-misc-cids.docx)\* & 12784, 12405, 10295, 12108 in [11-22/1733r1](https://mentor.ieee.org/802.11/dcn/22/11-22-1733-01-00be-cr-for-13-part-ii.docx) *[7 CIDs]*

**and incorporate the text changes into the latest TGbe draft.**

**Move: Edward Au Second: Rubayet Shafin**

**Discussion: None.**

**Result: Approved with unanimous consent.**

**Motion 482 (Withdrawal)**

**Move to approve “Rejected” resolutions to the CIDs:**

* 10284, 10875, 10297

**With the following rejection reason: “The commenter has withdrawn the comment”.**

**Move: Mike Montemurro Second: Binita Gupta**

**Discussion: None.**

**Result: Approved with unanimous consent.**

**Motion 483 (Quarantine 1)**

**Move to approve a resolution of:**

* **“Rejected -- A proposed resolution for “this CID” was discussed as part of the comment resolutions in “document”, however the group could not reach consensus on a proposed change that would resolve the comment.” for the listed “CIDs” in green font, wherein the detailed proposed resolution is shown in the last column of the table in** [**11-22/1773r11**](https://mentor.ieee.org/802.11/dcn/22/11-22-1773-10-00be-11-22-xxxx-00-lb266-crs-for-cids-in-quarantine-part-1.docx)

**Move: Stephen McCann Second: Abhishek Patil**

**Discussion: None.**

**Result: Approved with unanimous consent.**

**Motion 484 (Quarantine 2)**

**Move to approve a resolution of:**

* **“Rejected -- A proposed resolution for “this CID” was discussed as part of the comment resolutions in “document”, however the group could not reach consensus on a proposed change that would resolve the comment.” for the listed “CIDs”, wherein the detailed proposed resolution is shown in the last column of the table in** [**11-22/1849r3**](https://mentor.ieee.org/802.11/dcn/22/11-22-1849-03-00be-lb266-crs-for-cids-in-quarantine-part-2.docx)

**Move: Abhishek Patil Second: Po-Kai Huang**

**Discussion: None.**

**Result: Approved with unanimous consent.**

Note: CIDs that have been discussed and for which the group could not reach consensus. Contains rejections for certain CIDs that were discussed in these documents: 11-22/1335, 11-22/1373, 11-22/1381, 11-22/1454, 11-22/1457, 11-22/1477, 11-22/1500, 11-22/1501, 11-22/1503, 11-22/1509, 11-22/1582, 11-22/1586, 11-22/1690, 11-22/1746. Note that in R2 some of these CIDs are removed as per requests from members to be discussed separately (post-quarantine).

**Motion 485 (Post-Quarantine 1)**

**Move to approve a resolution of:**

* **“Revised – TGbe Editor to incorporate the changes as instructed by CID 13888”**

**for CID 13885**

**Move: Stephen McCann Second: Yanjun Sun**

**Discussion: None.**

**Result: Approved with unanimous consent.**

**Motion 486 (Post-Quarantine 3)**

**Move to approve resolutions to the CIDs:**

* 13587, 10039, 10863, 12726, 12728, 12892, 13588, 13813 in [11-22/1335r8](https://mentor.ieee.org/802.11/dcn/22/11-22-1335-08-00be-cr-for-cids-related-to-group-addressed-frame-reception-in-emlsr-nstr.docx) *[8 CIDs]*

**Move: Rubayet Shafin Second: Stephen McCann**

**Discussion: Some discussion.**

**Preliminary Result: 32Y, 37N, 30A (fails)**

**Result: 31Y, 37N, 30A (fails)**

Note: These were discussed on September 28, 2022, but no straw poll is conducted yet. Vishnu is POC. CIDs were present in 11-22/1849r0.

[V] Vishnu V Ratnam, Samsung Research America | X | | |

[V] Albert Bredewoud, Broadcom | | X | |

[V] Zinan Lin, InterDigital | | | X |

[v] Liwen Chu, NXP | X | | |

[NV] Yue Sunshine Qi, Samsung Research America | X | | | INVALID VOTE

[V] Al Petrick InterDigital | | | X |

[V} Peshal Nayak, Samsung Research America | X | | |

[V] Naveen Kakani, Qualcomm | | X | |

[V] Dong Wei, NXP | | | X |

[A] Zhi Mao, Huawei | | X | |

[V] Mengshi Hu Huawei | | X | |

[V] Jason Yuchen Guo Huawei | | X | |

[V] Yapu Li, OPPO | X | | |

[V] Yunbo Li, Huawei | | X | |

[V] Ming Gan Huawei | | X | |

[V] Yousi Lin Huawei | | | X |

[V]Jay. Yang Nokia | X | | |

[V]Guogang Huang Huawei | | | X |

Shivkumar Tadahal | | X | |

[V] Sindhu Verma Broadcom | | X | |

[V] Liuming Lu OPPO | X | | |

[V] Vamsi Amalladinne, Qualcomm Inc. | | X | |

[V] Gaurang Naik Qualcomm | | X | |

[V] Po-Kai Huang, intel | X | | |

Sang Kim | | | X |

[V] Chunyu Hu Meta | | X | |

[V] Li-Hsiang Sun, Mediatek | X | | |

[V] Yonggang Fang MediaTek | X | | |

[V] Youhan Kim, Qualcomm | | X | |

[V] Abdel Karim Ajami, Qualcomm | | X | |

[V] Yanjun Sun Qualcomm | | X | |

Yong Liu | | | X |

[V] Abhishek Patil Qualcomm | | X | |

Brian Hart | X | | |

[V] James Yee, MediaTek | | | X |

Jarkko Kneckt | | | X |

[V] Duncan Ho, Qualcomm | | X | |

[V] Minyoung Park, Intel | X | | |

Qi Wang | | | X |

Kaiying Lu | X | | |

[V] Rubayet Shafin, Samsung Research America | X | | |

[V] Morteza Mehrnoush, Meta | X | | |

[V] VK Jones - Qualcomm | | X | |

[V] Juan Fang, Intel | X | | |

[V] Dibakar Das, Intel | X | | |

[V] John Yi , Spreadtrum | | X | |

[V] Tianyu Wu Apple | | | X |

[V] Qing Xia, Sony | | | X |

[V] Xiaogang Chen ZEKU | | X | |

[V] Chao-Chun Wang Mediatek | X | | |

[V] Kanke Wu, Qualcomm | | X | |

[v] Matthew Fischer Broadcom | X | | |

[V] Srinivas Kandala Samsung | | X | |

[V] Sai Nanda [Synaptics] | X | | |

[V] Kapil Rai, Qualcomm | | X | |

[v] Rolf de Vegt Qualcomm | | X | |

[V] Thomas Pare, MediaTek | X | | |

[V] Pei Zhou, OPPO | X | | |

[V] Kazuto Yano, ATR | | | X |

[V] SunHee Baek, LGE | | | X |

[V] Xiangxin Gu, Unisoc | X | | |

[V] Eunsung Park LGE | | | X |

[V] Jinyoung Chun, LG | | | X |

[V] Sungjin Park, Senscomm | | | X |

[V] Jinsoo Choi LG | | | X |

[V] Greg Geonjung Ko WILUS | | | X |

[V] Yuki Tsujimaru Canon | | | X |

[V] Akira Kishida NTT | | | X |

[V] Sanghyun Kim WILUS Inc. | X | | |

Shubhodeep Adhikari | | X | |

[V] Romain GUIGNARD Canon | X | | |

[V] Jouni Malinen Qualcomm | | X | |

[V] Laurent Cariou, Intel | X | | |

[V] Mikael Lorgeoux Canon | X | | |

[V] Shimi Shilo Huawei | | | X |

[V] Massinissa Lalam, Sagemcom | | | X |

[V] Stephen McCann, Huawei | X | | |

[V] Pascal Viger, Canon | X | | |

[V] Geert Awater, Qualcomm | | X | |

[V] Stephane Baron Canon | X | | |

[V] Arik Klein Huawei | | | X |

[V] Thomas Handte Sony | | | X |

Sidharth Thakur | | X | |

[v] Raghvendra Gupta Broadcom | | X | |

[V] Xiaofei Wang InterDigital | | X | |

[V] Hanqing Lou InterDigital | | X | |

[V] Ray Yang, InterDigital | | | X |

[V] Joseph Levy, InterDigital | | | X |

[V] John Wullert, Peraton Labs | | | X |

[V] Kiseon Ryu NXP | | X | |

[V] Yan Xin Huawei | | X | |

[V] Binita Gupta, Meta | | X | |

[V] Mahmoud Kamel InterDigital | | | X |

[V] Junghoon Suh Huawei | X | | |

Edward Au, Huawei | | X | |

[V] Mike Montemurro Huawei | | | X |

[V] Gaurav Patwardhan | X | | |

Daniel Borges | | X | |

Lalit Garg | | X | |

* + 1321r3 CR-reducing-size-of-ML-Traffic-Indication Xiangxin Gu

C: some typo on the resolution collum.

C: did you run any SP for this CID?

A: No.

**SP:** Do you agree to resolve the following CIDs listed in 11-22/1321r4 and incorporate the text changes into the latest TGbe draft?

         10124

Discussion: None.

Result: No objection

* + 1815r1 CR-for-receiving-group-addressed-frames-during-EMLMR-frame-exchange Xiangxin Gu

C: Both eMLSR and eMLMR have this issue, we should also have similar text for eMLSR.

C: for eMLSR, it is not precluded that one link is receiving group addressed frame, and the other link is listening.

C: we had long discussion about this problem, and concluded with the current text in the draft spec, maybe eMLMR should also use similar text as eMLSR.

* + 1864r0 EPCS - MLD and EHT STA John Wullert

**SP:** Do you agree to resolve the following CIDs listed in 11-22/1864r0 and incorporate the text changes into the latest TGbe draft?

         11472

Discussion: None.

Result: No objection

* Adjourned at 11:57

# 6th Conf. Call: December 15 (10:00–12:00 ET)–MAC

Please refer to the following link for the minutes

* https://mentor.ieee.org/802.11/dcn/22/11-22-2080-05-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-nov-2022-to-jan-2023.docx

# 7th Conf. Call: December 19 (19:00–21:00 ET)–MAC

Please refer to the following link for the minutes

* https://mentor.ieee.org/802.11/dcn/22/11-22-2080-05-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-nov-2022-to-jan-2023.docx

# 8th Conf. Call: December 21 (10:00–12:00 ET)–MAC

Please refer to the following link for the minutes

* https://mentor.ieee.org/802.11/dcn/22/11-22-2080-05-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-nov-2022-to-jan-2023.docx

# 9th Conf. Call: January 04 (10:00–12:00 ET)–JOINT

* The Chair, Alfred Asterjadhi (Qualcomm), calls the meeting to order
* The Chair presents the IEEE 802 and 802.11 IPR policy and procedure
  + **Patent Policy: Ways to inform IEEE:**
    - Cause an LOA to be submitted to the IEEE-SA ([patcom@ieee.org](mailto:patcom@ieee.org)); or
    - Provide the chair of this group with the identity of the holder(s) of any and all such claims as soon as possible; or
    - Speak up now and respond to this Call for Potentially Essential Patents

If anyone in this meeting is personally aware of the holder of any patent claims that are potentially essential to implementation of the proposed standard(s) under consideration by this group and that are not already the subject of an Accepted Letter of Assurance, please respond at this time by providing relevant information to the WG Chair. **Nobody speaks/writes up**.

* + **Copyright Policy: Participants are advised that**
    - IEEE SA’s copyright policy is described in [Clause 7](https://standards.ieee.org/about/policies/bylaws/sect6-7.html#7) of the IEEE SA Standards Board Bylaws and [Clause 6.1](https://standards.ieee.org/about/policies/opman/sect6.html) of the IEEE SA Standards Board Operations Manual;
    - Any material submitted during standards development, whether verbal, recorded, or in written form, is a Contribution and shall comply with the IEEE SA Copyright Policy

**Copyright Policy was presented.**

* + **Patent, Participation, Copyright and policy related subclause:** Please refer to Patent And Procedures
* Attendance reminder.
  + Participation slide: <https://mentor.ieee.org/802-ec/dcn/16/ec-16-0180-05-00EC-ieee-802-participation-slide.pptx>
  + Please record your attendance during the conference call by using the IMAT system:
    - 1) login to [imat](https://imat.ieee.org/attendance), 2) select “802.11 Telecons (<Month>)” entry, 3) select “C/LM/WG802.11 Attendance” entry, 4) click “<Joint TGbe > conference call that you are attending.
  + If you are unable to record the attendance via [IMAT](https://imat.ieee.org/attendance) then please send an e-mail to Jason Y. Guo ([guoyuchen@huawei.com](mailto:guoyuchen@huawei.com)) and Alfred Asterjadhi ([asterjadhi@gmail.com](mailto:asterjadhi@gmail.com))
  + Please ensure that the following information is listed correctly when joining the call:
    - "[voter status] First Name Last Name (Affiliation)"
  + Attendee List

|  |  |  |  |
| --- | --- | --- | --- |
| Breakout | Timestamp | Name | Affiliation |
| TGbe (Joint)\* | 1/4 | Abdelaal, Rana | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | Aboulmagd, Osama | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 1/4 | Adhikari, Shubhodeep | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | Agarwal, Peyush | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | Ajami, Abdel Karim | Qualcomm Technologies, Inc |
| TGbe (Joint)\* | 1/4 | Alagarsamy, Srividhya | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | Amalladinne, Vamsi | Qualcomm Incorporated |
| TGbe (Joint)\* | 1/4 | Ansley, Carol | Cox Communications Inc. |
| TGbe (Joint)\* | 1/4 | Asterjadhi, Alfred | Qualcomm Incorporated |
| TGbe (Joint)\* | 1/4 | Au, Kwok Shum | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 1/4 | Baek, SunHee | LG ELECTRONICS |
| TGbe (Joint)\* | 1/4 | baron, stephane | Canon Research Centre France |
| TGbe (Joint)\* | 1/4 | Ben Arie, Yaron | toga networks(a huawei company) |
| TGbe (Joint)\* | 1/4 | Boldy, David | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | Bredewoud, Albert | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | Cao, Rui | NXP Semiconductors |
| TGbe (Joint)\* | 1/4 | Cariou, Laurent | Intel |
| TGbe (Joint)\* | 1/4 | Carney, William | Sony Group Corporation |
| TGbe (Joint)\* | 1/4 | Cavalcanti, Dave | Intel |
| TGbe (Joint)\* | 1/4 | Chang, Chen-Yi | Mediatek |
| TGbe (Joint)\* | 1/4 | Chen, Cheng | Intel |
| TGbe (Joint)\* | 1/4 | Chen, You-Wei | MediaTek Inc. |
| TGbe (Joint)\* | 1/4 | cheng, phoebe | MediaTek Inc. |
| TGbe (Joint)\* | 1/4 | CHENG, yajun | Xiaomi Communications Co., Ltd. |
| TGbe (Joint)\* | 1/4 | CHERIAN, GEORGE | Qualcomm Incorporated |
| TGbe (Joint)\* | 1/4 | Chiang, James | MediaTek Inc. |
| TGbe (Joint)\* | 1/4 | Choi, Jinsoo | LG ELECTRONICS |
| TGbe (Joint)\* | 1/4 | Chu, Liwen | NXP Semiconductors |
| TGbe (Joint)\* | 1/4 | CHUN, JINYOUNG | LG ELECTRONICS |
| TGbe (Joint)\* | 1/4 | Coffey, John | Realtek Semiconductor Corp. |
| TGbe (Joint)\* | 1/4 | Das, Subir | Peraton Labs |
| TGbe (Joint)\* | 1/4 | Derham, Thomas | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | de Vegt, Rolf | Qualcomm Incorporated |
| TGbe (Joint)\* | 1/4 | Dong, Xiandong | Xiaomi Communications Co., Ltd. |
| TGbe (Joint)\* | 1/4 | Erkucuk, Serhat | Ofinno |
| TGbe (Joint)\* | 1/4 | Fan, Shuang | ZTE Corporation |
| TGbe (Joint)\* | 1/4 | Fang, Yonggang | Mediatek |
| TGbe (Joint)\* | 1/4 | Fischer, Matthew | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | Fujimori, Yuki | Canon Research Centre France |
| TGbe (Joint)\* | 1/4 | Garg, Lalit | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | Gong, Bo | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 1/4 | Gu, Xiangxin | Unisoc |
| TGbe (Joint)\* | 1/4 | GUIGNARD, Romain | Canon Research Centre France |
| TGbe (Joint)\* | 1/4 | Guo, Yuchen | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 1/4 | Gupta, Binita | Meta Platforms, Inc. |
| TGbe (Joint)\* | 1/4 | Haider, Muhammad Kumail | Meta Platforms Inc. |
| TGbe (Joint)\* | 1/4 | Handte, Thomas | Sony Corporation |
| TGbe (Joint)\* | 1/4 | Hervieu, Lili | Cable Television Laboratories Inc. (CableLabs) |
| TGbe (Joint)\* | 1/4 | Ho, Duncan | Qualcomm Incorporated |
| TGbe (Joint)\* | 1/4 | Hotchkiss, Ron | IEEE STAFF |
| TGbe (Joint)\* | 1/4 | Hu, Chunyu | Facebook |
| TGbe (Joint)\* | 1/4 | HUANG, CHIHAN | MediaTek Inc. |
| TGbe (Joint)\* | 1/4 | Huang, Po-Kai | Intel |
| TGbe (Joint)\* | 1/4 | Huq, Kazi Mohammed Saidul | Ofinno |
| TGbe (Joint)\* | 1/4 | Jang, Insun | LG ELECTRONICS |
| TGbe (Joint)\* | 1/4 | Ji, Chenhe | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 1/4 | Jung, Insik | LG ELECTRONICS |
| TGbe (Joint)\* | 1/4 | Kakani, Naveen | Qualcomm Incorporated |
| TGbe (Joint)\* | 1/4 | kamath, Manoj | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | Kamel, Mahmoud | InterDigital, Inc. |
| TGbe (Joint)\* | 1/4 | Kandala, Srinivas | SAMSUNG |
| TGbe (Joint)\* | 1/4 | Kasher, Assaf | Qualcomm Incorporated |
| TGbe (Joint)\* | 1/4 | Kim, Jeongki | Ofinno |
| TGbe (Joint)\* | 1/4 | Kim, Sang Gook | LG ELECTRONICS |
| TGbe (Joint)\* | 1/4 | Kim, Sanghyun | WILUS Inc |
| TGbe (Joint)\* | 1/4 | Kishida, Akira | Nippon Telegraph and Telephone Corporation (NTT) |
| TGbe (Joint)\* | 1/4 | Klein, Arik | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 1/4 | Kneckt, Jarkko | Apple, Inc. |
| TGbe (Joint)\* | 1/4 | Ko, Geonjung | WILUS Inc. |
| TGbe (Joint)\* | 1/4 | Koundourakis, Michail | Samsung Cambridge Solution Centre |
| TGbe (Joint)\* | 1/4 | Lalam, Massinissa | SAGEMCOM BROADBAND SAS |
| TGbe (Joint)\* | 1/4 | Lanante, Leonardo | Ofinno |
| TGbe (Joint)\* | 1/4 | Lansford, James | Qualcomm Incorporated |
| TGbe (Joint)\* | 1/4 | Levy, Joseph | InterDigital, Inc. |
| TGbe (Joint)\* | 1/4 | Li, Yapu | Guangdong OPPO Mobile Telecommunications Corp.,Ltd |
| TGbe (Joint)\* | 1/4 | Li, Yunbo | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 1/4 | Lim, Dong Guk | LG ELECTRONICS |
| TGbe (Joint)\* | 1/4 | Lin, Hsin-De | MediaTek Inc. |
| TGbe (Joint)\* | 1/4 | LIU, CHENCHEN | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 1/4 | Lorgeoux, Mikael | Canon Research Centre France |
| TGbe (Joint)\* | 1/4 | Lou, Hanqing | InterDigital, Inc. |
| TGbe (Joint)\* | 1/4 | Lu, kaiying | MediaTek Inc. |
| TGbe (Joint)\* | 1/4 | Lu, Liuming | Guangdong OPPO Mobile Telecommunications Corp.,Ltd |
| TGbe (Joint)\* | 1/4 | Mak, Siukai | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | Mantha, Abhishek | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | MAO, ZHI | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 1/4 | Max, Sebastian | Ericsson AB |
| TGbe (Joint)\* | 1/4 | McCann, Stephen | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 1/4 | Mehrnoush, Morteza | Facebook |
| TGbe (Joint)\* | 1/4 | Moelker, Dignus-Jan | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | Montemurro, Michael | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 1/4 | Montreuil, Leo | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | Naik, Gaurang | Qualcomm Technologies, Inc |
| TGbe (Joint)\* | 1/4 | Nezou, Patrice | Canon Research Centre France |
| TGbe (Joint)\* | 1/4 | Palm, Stephen | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | Pandey, Sheetal | Synaptics Inc. |
| TGbe (Joint)\* | 1/4 | Park, Sungjin | Senscomm |
| TGbe (Joint)\* | 1/4 | Patil, Abhishek | Qualcomm Incorporated |
| TGbe (Joint)\* | 1/4 | Patwardhan, Gaurav | Hewlett Packard Enterprise |
| TGbe (Joint)\* | 1/4 | Petrick, Albert | InterDigital, Inc. |
| TGbe (Joint)\* | 1/4 | Prabhakaran, Dinakar | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | Puducheri, Srinath | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | Qi, Yue | Samsung Research America |
| TGbe (Joint)\* | 1/4 | Quan, Yingqiao | Unisoc |
| TGbe (Joint)\* | 1/4 | Ratnam, Vishnu | Samsung Research America |
| TGbe (Joint)\* | 1/4 | Redlich, Oded | Huawei Technologies Co., Ltd; Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 1/4 | Regev, Dror | Toga Networks (A Huawei Company) |
| TGbe (Joint)\* | 1/4 | REICH, MOR | Togan Networks, a Huawei Company |
| TGbe (Joint)\* | 1/4 | Rosdahl, Jon | Qualcomm Technologies, Inc. |
| TGbe (Joint)\* | 1/4 | Ryu, Kiseon | NXP Semiconductors |
| TGbe (Joint)\* | 1/4 | Seo, Sangho | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | Shafin, Rubayet | Samsung Research America |
| TGbe (Joint)\* | 1/4 | Shilo, Shimi | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 1/4 | SUH, JUNG HOON | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 1/4 | Sun, Li-Hsiang | MediaTek Inc. |
| TGbe (Joint)\* | 1/4 | Sun, Yanjun | Qualcomm Incorporated |
| TGbe (Joint)\* | 1/4 | Tsai, Tsung-Han | MediaTek Inc. |
| TGbe (Joint)\* | 1/4 | Tsodik, Genadiy | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 1/4 | Val, Inaki | MaxLinear |
| TGbe (Joint)\* | 1/4 | Verma, Sindhu | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | VIGER, Pascal | Canon Research Centre France |
| TGbe (Joint)\* | 1/4 | Wang, Chao Chun | MediaTek Inc. |
| TGbe (Joint)\* | 1/4 | Wang, Hao | Tencent |
| TGbe (Joint)\* | 1/4 | Wang, Qi | Apple, Inc. |
| TGbe (Joint)\* | 1/4 | Wei, Dong | NXP Semiconductors |
| TGbe (Joint)\* | 1/4 | Wentink, Menzo | Qualcomm Incorporated |
| TGbe (Joint)\* | 1/4 | Wullert, John | Peraton Labs |
| TGbe (Joint)\* | 1/4 | Xin, Yan | Huawei Technologies Co., Ltd |
| TGbe (Joint)\* | 1/4 | Xu, Fangxin | Longsailing Semiconductor |
| TGbe (Joint)\* | 1/4 | Yanamandra, Subrahmanyam | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | Yang, Jay | Nokia |
| TGbe (Joint)\* | 1/4 | YANG, RUI | InterDigital, Inc. |
| TGbe (Joint)\* | 1/4 | Yano, Kazuto | Advanced Telecommunications Research Institute International (ATR) |
| TGbe (Joint)\* | 1/4 | Yee, James | MediaTek Inc. |
| TGbe (Joint)\* | 1/4 | Yi, Yongjiang | Spreadtrum Communication USA, Inc |
| TGbe (Joint)\* | 1/4 | Young, Christopher | Broadcom Corporation |
| TGbe (Joint)\* | 1/4 | Zhang, Jiayi | Ofinno |
| TGbe (Joint)\* | 1/4 | Zhou, Lei | H3C Technologies Co., Limited |
| TGbe (Joint)\* | 1/4 | Zhou, Pei | Guangdong OPPO Mobile Telecommunications Corp.,Ltd |

* Announcements:
  + TGbe MAC ad-hoc scheduled next week in San Diego (11-13th January, 2023)
    - Please make sure that submissions in the MAC queues are uploaded on mentor a day before the MAC ad-hoc so that we can organize the agenda.
* Agenda
  + Technical Submissions**: CRs**
    - 1482r3 CR for preamble puncturing Yanjun Sun [2C-SP 10’]
    - 2157r0 CR for misc. LB266 comments Edward Au [28C 20’]
    - 2209r0 CR for misc. LB266 comments-Part 2 Edward Au [12C 10’]
    - 2180r0 LB266-General CID Alfred Asterjadhi [1C 10’]
    - 1692r2 Clause 3.2 Comment Resolutions Stephen McCann [2C 10’]
    - 1851r0 CR for CID 11891 Chenchen LIU [1C 10’]
    - 1348r2 CR for PAR verification low latency Yousi Lin [1C 10’]
    - 1878r0 CR-for-Clause-6.3 Arik Klein [3C 10’]
    - 2125r0 LB266 CR for Trigger frame Misc Part2 Yanjun Sun [3C 10’]
    - 2126r0 LB266 CR for Preamble Puncturing Misc Yanjun Sun [3C 10’]
  + Motions (second hour): [1038r](https://mentor.ieee.org/802.11/dcn/22/11-22-1038-33-00be-tgbe-motions-list-part-3.pptx)33
  + Discussions
    - None
  + Agenda approved with unanimous consent
* Discussions of the Technical Submissions**: CRs**
  + 1482r3 CR for preamble puncturing Yanjun Sun

C: for 320MHz, N can be 1, 2, 4 or 8, but you only mention N=8.

C: if you change the text like this, it’s not very clear to me.

C: suggest to add a small table, capturing different values of N and the bandwidth.

C: the value N is defined for EHT STAs, or defined for EHT and legacy STAs?

A: for Both.

C: prepare the table before the face to face meeting.

SP deferred.

* + 2157r0 CR for misc. LB266 comments Edward Au

C: Zero elements or one element?

A: need to check with TGm.

C: for EPCS, the initials can be capital letters since I find some other examples in TGme

A: need to submit comments for TGme to fix them.

**SP:** Do you agree to resolve the following CIDs listed in 11-22/2157r1 and incorporate the text changes into the latest TGbe draft?

         10074, 10135, 10136, 10137, 10138, 10139, 10140, 10141, 10215, 10353,10579, 13716, 11845, 12976, 10755, 10756, 11478, 11489, 11833, 12247, 12955, 13724, 11822, 11901, 11976, 12499, 13713

Discussion: None.

Result: No objection

* + 2209r0 CR for misc. LB266 comments-Part 2 Edward Au

C: “authenticator” should be capitalized.

**SP:** Do you agree to resolve the following CIDs listed in 11-22/2209r0 and incorporate the text changes into the latest TGbe draft?

         12079, 13749, 13750, 14002, 13746, 12366, 12367, 12152, 13123, 13188, 11985, 12982

Discussion: None.

Result: No objection

* + Motions

**Motion 487 (MAC)**

**Move to approve resolutions to the CIDs:**

* 10279, 10342, 10343, 10344, 10446, 10447, 10528, 10898, 12087, 12282, 12364, 12950, 13045 in [11-22/1260r2](https://mentor.ieee.org/802.11/dcn/22/11-22-1260-02-00be-cr-for-5-1-5-1-architecture-part-2.docx) *[13 CIDs]*
* 10068, 11072, 11073, 11939, 13601 in [11-22/2033r1](https://mentor.ieee.org/802.11/dcn/22/11-22-2033-01-00be-cr-for-miscellaneous-cids-ii.docx) &14097 in [11-22/1669r3](https://mentor.ieee.org/802.11/dcn/22/11-22-1669-03-00be-lb266-cr-for-35-2-3.docx) & 12610 in [11-22/1771r1](https://mentor.ieee.org/802.11/dcn/22/11-22-1771-01-00be-lb266-cr-for-9-6-35-8.docx) *[7 CIDs]*
* 12713, 13387, 13666, 13390, 12817, 10325 in [11-22/1900r2](https://mentor.ieee.org/802.11/dcn/22/11-22-1900-02-00be-lb266-cr-for-remaining-cids.docx) &12886, 13400, 13674, 13703 in [11-22/2045r0](https://mentor.ieee.org/802.11/dcn/22/11-22-2045-00-00be-lb266-cr-misc-part2.docx) *[10 CIDs]*
* 10369, 10509, 11383 in [11-22/1743r3](https://mentor.ieee.org/802.11/dcn/22/11-22-1743-03-00be-lb266-cr-for-emlmr-supported-mcs-and-nss-set-related-cids.docx) & 12782, 12109, 10296 in [11-22/1736r3](https://mentor.ieee.org/802.11/dcn/22/11-22-1736-03-00be-cr-for-13-part-iii.docx) & 10355, 11601 in [11-22/1864r0](https://mentor.ieee.org/802.11/dcn/22/11-22-1864-00-00be-epcs-mld-and-eht-sta.docx) *[8 CIDs]*
* 13284 in [11-22/1765r1](https://mentor.ieee.org/802.11/dcn/22/11-22-1765-01-00be-cr-for-cid-13284.docx) & 14115 in [11-22/1848r2](https://mentor.ieee.org/802.11/dcn/22/11-22-1848-02-00be-lb266-cr-misc.docx) & 14099 in [11-22/1973r1](https://mentor.ieee.org/802.11/dcn/22/11-22-1973-01-00be-cr-for-cid14099.docx) & 12070 in [11-22/1775r2](https://mentor.ieee.org/802.11/dcn/22/11-22-1775-02-00be-lb266-cr-for-9-4-2-164.docx) *[4 CIDs]*

and incorporate the text changes into the latest TGbe draft.

**Move: Mike Montemurro Second: Chunyu Hu**

**Discussion:** Need to Check 11472 in doc 1864, it’s missing. Edward commented that it is ready for motion. It turns out that this CID is captured in Motion 489.

**Result: Approved with unanimous consent.**

**Motion 488 (MAC)**

**Move to approve resolutions to the CIDs:**

* 13854 in [11-22/1898r2](https://mentor.ieee.org/802.11/dcn/22/11-22-1898-02-00be-lb-266-cr-for-emlsr-misc-2.docx) & 11778, 12716 in [11-22/2059r0](https://mentor.ieee.org/802.11/dcn/22/11-22-2059-00-00be-lb266-cr-for-cid-11778-and-12716.docx) & 12604, 13263, 13264 in [11-22/1890r3](https://mentor.ieee.org/802.11/dcn/22/11-22-1890-03-00be-lb266-cr-for-reconfiguration-ml-element.docx) *[6 CIDs]*
* 10287, 11545, 11546, 11549, 11550, 11551, 13712 in [11-22/2108r2](https://mentor.ieee.org/802.11/dcn/22/11-22-2108-02-00be-cr-for-misc-cids.docx) *[7 CIDs]*
* 13753, 14113, 11518, 11515, 10558, 12739, 12740, 12058, 12933 in [11-22/1480r1](https://mentor.ieee.org/802.11/dcn/22/11-22-1480-01-00be-lb266-cr-for-clause-9.docx) *[9 CIDs]*
* 10011, 10075, 12458, 12721, 12722, 12754, 13857, 13879, 13880, 13214, 10217, 10738, 10970, 11834, 11017, 11521, 12420, 12480, 13255, 14030, 14025, 12489, 12321 in [11-22/1909r3](https://mentor.ieee.org/802.11/dcn/22/11-22-1909-03-00be-txs-related-cids-part-2.docx) *[23 CIDs]*
* 13708, 11465, 12875, 12876, 10162, 13877, 10159, 10160, 10161, 12684, 12452, 12166, 11466 in [11-22/1504r2](https://mentor.ieee.org/802.11/dcn/22/11-22-1504-02-00be-11be-d2-0-comment-resolution-subclause-35-3-18-part-2.docx) *[13 CIDs]*

**and incorporate the text changes into the latest TGbe draft.**

**Move: Xiaofei Wang Second: Stephen McCann**

**Discussion: None.**

**Result: Approved with unanimous consent.**

**Motion 489 (Joint)**

**Move to approve resolutions to the CIDs:**

* 11827 in [11-22/1695r1](https://mentor.ieee.org/802.11/dcn/22/11-22-1695-01-00be-cr-on-cid-11827-and-12115.docx) & 13550, 13958, 10802, 10957, 12491, 12492, 14052, 14050 in [11-22/1565r3](https://mentor.ieee.org/802.11/dcn/22/11-22-1565-03-00be-lb266-cr-for-uora.docx) *[9 CIDs]*
* 10979, 10958, 13549, 13440, 10813 in [11-22/2123r0](https://mentor.ieee.org/802.11/dcn/22/11-22-2123-00-00be-lb266-cr-for-trigger-frame-misc-part1.docx) & 10124 in [11-22/1321r4](https://mentor.ieee.org/802.11/dcn/22/11-22-1321-04-00be-cr-reducing-size-of-ml-traffic-indication.docx) & 11472 in [11-22/1864r0](https://mentor.ieee.org/802.11/dcn/22/11-22-1864-00-00be-epcs-mld-and-eht-sta.docx) *[7 CIDs]*

**and incorporate the text changes into the latest TGbe draft.**

**Move: Stephen McCann Second: Xiaofei Wang**

**Discussion: None.**

**Result: Approved with unanimous consent.**

**Motion 490 (Withdrawal)**

**Move to approve “Rejected” resolutions to the CIDs:**

* 13737, 14101, 11240, 11242, 10611, 10561, 10452, 11056\*

**With the following rejection reason: “The commenter has withdrawn the comment”.**

**Move: Binita Gupta Second: Mike Montemurro**

**Discussion: None.**

**Result: Approved with unanimous consent.**

**Motion 491 (Quarantine 1)**

**Move to approve a resolution of:**

* **“Rejected -- A proposed resolution for “this CID” was discussed as part of the comment resolutions in “document”, however the group could not reach consensus on a proposed change that would resolve the comment.” for the listed “CIDs” highlighted in green, wherein additional details for the proposed resolution are shown in the last column of the table in** [**11-22/1849r5**](https://mentor.ieee.org/802.11/dcn/22/11-22-1849-05-00be-lb266-crs-for-cids-in-quarantine-part-2.docx)

**Move: Stephen McCann Second: Stephen Palm**

**Discussion: None.**

**Result: Approved with unanimous consent.**

**Motion 492 (Post-Quarantine 1)**

**Move to approve resolutions to the CIDs:**

* 13819, 10659, 13844 in [11-22/1767r2](https://mentor.ieee.org/802.11/dcn/22/11-22-1767-02-00be-lb266-cr-for-nonprimary-link-channel-switch.docx) [3 CIDs]

**Move: Sanghyun Kim Second: Geonjung Ko**

**Discussion: Overview provided by author. No further comments.**

**Result: Approved with unanimous consent.**

**Motion 493 (Post-Quarantine 2)**

**Move to approve resolutions to the CIDs:**

* 12036 in [11-22/1366r1](https://mentor.ieee.org/802.11/dcn/22/11-22-1366-01-00be-cr-for-miscellaneous-cids.docx) [1 CID]

**Move: Second:**

**Discussion:**

Binita: The commenter is asking about the affiliated AP. You should add a term “affiliated AP” and explain that.

Abhi: the original version looks better.

**Result: Postponed to F2F.**

**Motion 494 (Post-Quarantine 3)**

**Move to approve resolutions to the CIDs:**

* 10385, 10436, 10486, 10632, 10722, 10771, 10772, 11102, 11428, 11742, 12163, 12164, 12168, 12169, 12377, 12378, 12481, 12906, 13092, 13277, 12165, 10717, 11658, 13066 in [11-22/2042r0](https://mentor.ieee.org/802.11/dcn/22/11-22-2042-00-00be-lb266-cr-for-ml-reconfiguration.docx) *[24 CIDs]*

**Move: Yongho Seok Second: Ming Gan**

**Discussion: Some discussion.**

**Preliminary Result: 42Y, 70N, 16A (fails)**

**Result: 42Y, 70N, 15A (fails)**

[V] Vishnu V Ratnam, Samsung Research America | | | X |

[V] Al Petrick InterDigital | | X | |

[V] Chunyu Hu Meta | | X | |

[V] Rubayet Shafin, Samsung Research America | | | X |

[V} Peshal Nayak, Samsung Research America | | | X |

[V] Naveen Kakani, Qualcomm | | X | |

[V] Rolf de Vegt, Qualcomm | | X | |

[V] Srinath Puducheri Broadcom | | X | |

[A] Zhi Mao, Huawei | X | | |

[V] Jason Yuchen Guo Huawei | X | | |

[V] Ross Jian Yu Huawei | X | | |

[V] Bo Gong Huawei | X | | |

[V]Chenchen LiuHuawei | X | | |

[V]Guogang Huang Huawei | X | | |

[V] Yunbo Li, Huawei | X | | |

[V] Yousi Lin | X | | |

[V] Ming Gan Huawei | X | | |

[V] Mengshi Hu Huawei | X | | |

[V] BO SUN, Sanechips | | X | |

[V] Zhenguo Du, Huawei | X | | |

[V] Hank Chihan Huang, MediaTek | X | | |

[V] Harry Hao Wang Tencent | | X | |

[V] Hsin-De Lin Mediatek, Inc. | X | | |

[V] James Chiang, MediaTek | X | | | WebEx Chat

[V] Kevin Tsunghan Tsai, Mediatek | X | | |

[V] Phoebe ShuMin Cheng, Mediatek | X | | |

Wei Lin | X | | |

[V] Eason Chen-Yi Chang, Mediatek | X | | |

[V] Lan Peng Huawei | X | | |

[V] Duncan Ho Qualcomm | | X | |

[v] Matthew Fischer Broadcom | X | | |

Qi Wang | | X | |

[V] Binita Gupta, Meta | | X | |

[V] Abdel Karim Ajami, Qualcomm | | X | |

Jarkko Kneckt | | X | |

[V] Yonggang Fang MediaTek | X | | |

[V] Jon Rosdahl, Qualcomm | | X | |

[V] George Cherian Qualcomm | | X | |

[V] Yanjun Sun Qualcomm | | X | |

Yong Liu | | X | |

[V] Mike Montemurro Huawei | | X | |

[V] Gaurang Naik Qualcomm | | X | |

[V] Yongho Seok MediaTek | X | | |

[V]Kaiying Lu MediaTek USA | X | | |

[V] Abhishek Patil Qualcomm | | X | | WebEx Chat

[V] M. Kumail Haider Meta | | X | |

[V] Tianyu Wu Apple | | | X |

[V] Srinivas Kandala Samsung | | X | | WebEx Chat

[V]Sangho Seo, Broadcom | | X | |

Thomas Derham | | X | |

[V]Chao-Chun Wang Mediatek | X | | |

[V] kiwin PALM [BRCM] | | X | | WebEx Chat

[V] Gaurav Patwardhan HPE | | X | |

[V] Lalit Garg, Broadcom | | X | | WebEx Chat

[V] Vamsi Amalladinne, Qualcomm Inc. | | X | | WebEx Chat

[V] Cheng Chen, Intel | | X | | WebEx Chat

[V] Dibakar Das, Intel | | X | | WebEx Chat

[V] Juan Fang, Intel | | X | |

[V] VK Jones Qualcomm Inc | | X | | WebEx Chat

Zhou Lan | | X | |

Sang Kim | | X | |

[Mediatek] Gabor Bajko | X | | |

[V] You-Wei Chen, Mediatek | X | | | WebEx Chat

Brian Hart | | X | |

[V] Rana Abdelaal (Broadcom) | | X | |

[V] Kazuto Yano, ATR | X | | |

[V] Insun Jang LGE | | X | |

[V] Jeongki Kim Ofinno | | | X |

[V] Serhat Erkucuk, Ofinno | X | | |

[V] Jinsoo Choi LG | | X | |

Shawn Kim, WILUS Inc. | | X | |

[V] Eunsung Park LGE | | X | |

[V] SunHee Baek LGE | | X | |

[V] Chenhe Ji Huawei | X | | |

[V] Jinyoung Chun, LG | | X | |

[V] Akira Kishida NTT | | | X |

[V] Myeongjin Kim Samsung | | | X |

[V] Bruce HaoHua Kang, MediaTek | X | | | WebEx Chat

[V] Steven Qi Wang Huawei | X | | |

[V] Frank Chien-Fang Hsu, Mediatek | X | | |

Edward Au, Huawei | | | X |

[V] Kazi Huq, Ofinno | | | X |

[V] Osama Aboul-Magd, Huawei | X | | |

[V] Carol Ansley Cox | | X | |

[V] Kiseon Ryu NXP | | X | |

[V] Li-Hsiang Sun, Mediatek | X | | |

[V] Leonardo Lanante, Ofinno | X | | |

[V] Mahmoud Kamel InterDigital | | X | | WebEx Chat

[V] Chung-Ta Ku, Mediatek | X | | | WebEx Chat

[V] Jung Hoon Suh Huawei | X | | |

[V] Shubhodeep Adhikari Broadcom | | X | |

[V] Dinakar Prabhakaran Broadcom | | X | |

Shivkumar Tadahal | | X | | WebEx Chat

[V] manoj rk broadcom | | X | |

[V] John Wullert, Peraton Labs | | X | |

[V] Zinan Lin, InterDigital | | X | |

[V] Ray Yang, InterDigital | | | X |

[V] Xiaofei Wang InterDigital | | X | |

[V] Hanqing Lou InterDigital | | X | |

[V] Joseph Levy, InterDigital | | X | | WebEx Chat

[V] Yan Xin Huawei | X | | | WebEx Chat

[V] Oded Redlich, Huawei | | | X |

[V] Genadiy Tsodik Huawei | | | X |

[V] Michail Koundourakis, Samsung | | X | |

[V] Massinissa Lalam, Sagemcom | X | | |

[V] Jim Lansford Qualcomm | | X | |

[V] Stephane Baron Canon | | X | |

[V] Patrice NEZOU, Canon | | X | |

[V] Pascal Viger, Canon | | X | |

[NV] Inaki Val, MaxLinear | | | X | INVALID VOTE: NON VOTER

[V] Shimi Shilo Huawei | X | | |

[V] Romain GUIGNARD Canon | | X | |

[V] Laurent Cariou, Intel | | X | |

[V] Mikael Lorgeoux Canon | | X | |

[V] Arik Klein Huawei | | X | |

[V] Allert van Zelst, Qualcomm | | X | |

[V] Stephen McCann, Huawei | | | X | WebEx Chat

[V] Menzo Wentink Qualcomm | X | | |

[V] Yaron Benarie Huawei | | | X | WebEx Chat

[V] Albert Bredewoud, Broadcom | | X | |

[V] David Boldy Broadcom | | X | | WebEx Chat

[V] Dignus-Jan Moelker, Broadcom | | | X |

Assaf Kasher, [Qualcomm] | | X | | WebEx Chat

[V] Dror Regev Huawei | | X | |

[V] Bin Tian Qualcomm | | X | |

[V] Lin Yang Qualcomm | | X | |

[V] Morteza Mehrnoush, Meta | X | | |

[V] Sean Coffey Realtek | | X | |

**Motion 495 (Post-Quarantine 4)**

**Move to approve resolutions to the CIDs:**

* 12510, 11542, 11544, 13256 in [11-22/1316r2](https://mentor.ieee.org/802.11/dcn/22/11-22-1316-02-00be-cr-for-35-3-1.docx) *[4 CIDs]*

**Move: Po-Kai Huang Second: Binita Gupta**

**Discussion: Some clarification questions.**

**Result: Approved with unanimous consent.**

* Adjourned at 11:57

# 10th Conf. Call: January 05 (10:00–12:00 ET)–MAC

Please refer to the following link for the minutes

* https://mentor.ieee.org/802.11/dcn/22/11-22-2080-06-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-nov-2022-to-jan-2023.docx

# TGbe January 2023 MAC ad-hoc meetings

Please refer to the following link for the minutes

* https://mentor.ieee.org/802.11/dcn/23/11-23-0054-02-00be-minutes-for-tgbe-mac-ad-hoc-meeting-in-january-2023.docx